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DE3831787

Biblio

Desc

Claims

Drawing

esp@cenet

Adhesion bonding method

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Applicant(s): PASCAL ROGER (FR)

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EC Classification: [B29C65/34](#), [C09J5/06](#)

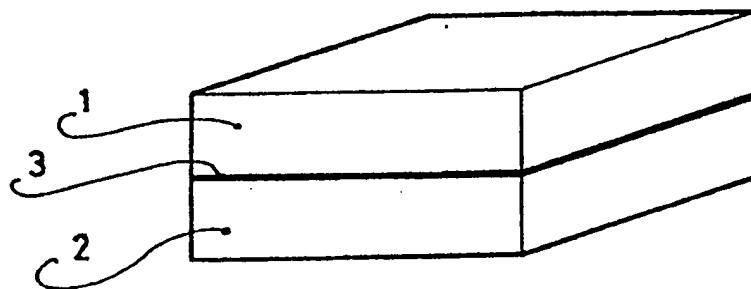
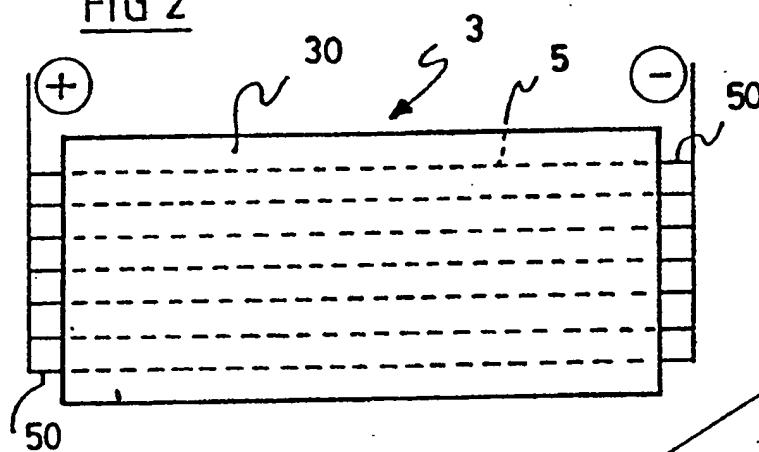
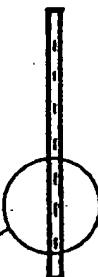
Equivalents: [ES2008030](#), [FR2620648](#), [JP1163283](#)

Abstract

Method of bonding two elements, in which the adhesion element used is an adhesive heated by a heating element which in turn is formed by a conductive resistance element incorporated into the adhesion element. The conductive element may be a metal wire, for example of copper, steel or constantan, and may have the form of a lattice or of essentially parallel wires or fibres. The conducting element is supplied with electrical current.

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FIG 1FIG 2FIG 3FIG 3aFIG 3'a